



Part Number:101-00318-**
SIM + Micro SD P/P Card Conn.

- Push-push eject type
- SMT
- Application for mobile phones

1. Materials:

Housing: High temperature thermoplastic,
 UL 94V-0 rated.
 Contact: Copper alloy
 Cover: SUS304 over nickel plating (50μ" min)

2. Contact finish:

Selective 1~15μ" gold plating on contact area,
 tin 160μ" plating at solder tail, over nickel
 plating (50μ" min)

3. Electrical specifications:

Voltage Rating: 100VAC
 Current Rating: 0.5A per contact
 Dielectric strength: 500VAC initial and 250VAC
 final for one minute
 Insulation Resistance: 1000MΩ min at 500VDC
 Contact Resistance: 100mΩ max at 100mA
 Operating temperature: -25°C~+70°C

4. Mechanical specifications:

Durability: 5000cycles.
 Micro SD Card Mating force: 13.8N max.
 Micro SD Card Unmating force: 1N max
 Sim Card Mating force: 10N max.
 Sim Card Unmating force: 0.3N max

5. RoHS Compliant

